



**THE DATASHEET OF
FIN1025MTCX**



FIN1025

3.3V LVDS 2-Bit High Speed Differential Driver

General Description

This dual driver is designed for high speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. The driver translates LVTTTL signal levels to LVDS levels with a typical differential output swing of 350mV which provides low EMI at ultra low power dissipation even at high frequencies. This device is ideal for high speed transfer of clock and data.

The FIN1025 can be paired with its companion receiver, the FIN1026, or any other LVDS receiver.

Features

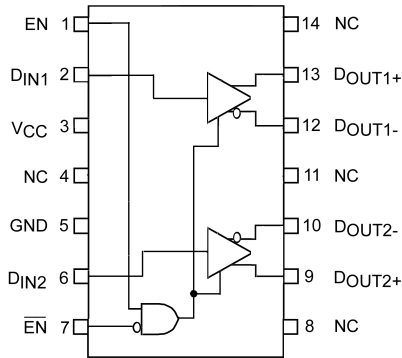
- Greater than 400Mbps data rate
- Flow-through pinout simplifies PCB layout
- 3.3V power supply operation
- 0.4ns maximum differential pulse skew
- 1.7ns maximum propagation delay
- Low power dissipation
- Power-Off protection
- Meets or exceeds the TIA/EIA-644 LVDS standard
- 14-Lead TSSOP package saves space

Ordering Code:

Order Number	Package Number	Package Description
FIN1025MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Pin Descriptions

Pin Name	Description
D _{IN1} , D _{IN2}	LVTTTL Data Inputs
D _{OUT1+} , D _{OUT2+}	Non-Inverting Driver Outputs
D _{OUT1-} , D _{OUT2-}	Inverting Driver Outputs
EN	Driver Enable Pin
$\overline{\text{EN}}$	Inverting Driver Enable Pin
V _{CC}	Power Supply
GND	Ground
NC	No Connect

Truth Table

Inputs			Outputs	
EN	$\overline{\text{EN}}$	D _{IN}	D _{OUT+}	D _{OUT-}
H	L or OPEN	H	H	L
H	L or OPEN	L	L	H
H	L or OPEN	OPEN	L	H
X	H	X	Z	Z
L or OPEN	X	X	Z	Z

H = HIGH Logic Level
L = LOW Logic Level
X = Don't Care
Z = High Impedance

Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC})	-0.5V to +4.6V
LVTTTL DC Input Voltage (V_{IN})	-0.5V to +6V
LVDS DC Output Voltage (V_{OUT})	-0.5V to 4.6V
Driver Short Circuit Current (I_{OSD})	Continuous
Storage Temperature Range (T_{STG})	-65°C to +150°C
Max Junction Temperature (T_J)	150°C
Lead Temperature (T_L) (Soldering, 10 seconds)	260°C
ESD (Human Body Model)	10,000V
ESD (Machine Model)	600V

Recommended Operating Conditions

Supply Voltage (V_{CC})	3.0V to 3.6V
Input Voltage (V_{IN})	0 to V_{CC}
Operating Temperature (T_A)	-40°C to +85°C

Note 1: The "Absolute Maximum Ratings": are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specification.

DC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 2)	Max	Units
V_{OD}	Output Differential Voltage	$R_L = 100\Omega$, Driver Enabled, See Figure 1	250	340	450	mV
ΔV_{OD}	V_{OD} Magnitude Change from Differential LOW-to-HIGH			1.4	25	mV
V_{OS}	Offset Voltage		1.125	1.25	1.375	V
ΔV_{OS}	Offset Magnitude Change from Differential LOW-to-HIGH			1.2	25	mV
V_{OH}	HIGH Output Voltage	$V_{IN} = V_{CC}$, $R_L = 100\Omega$		1.4	1.6	V
V_{OL}	LOW Output Voltage	$V_{IN} = 0V$, $R_L = 100\Omega$	0.9	1.05		V
I_{OFF}	Power Off Output Current	$V_{CC} = 0V$, $V_{OUT} = 0V$ or 3.6V	-20		20	μA
I_{OS}	Short Circuit Output Current	$V_{OUT} = 0V$, Driver Enabled		-3	-6	mA
		$V_{OD} = 0V$, Driver Enabled		-3.5	-6	
V_{IH}	Input HIGH Voltage		2.0		V_{CC}	V
V_{IL}	Input LOW Voltage		GND		0.8	V
I_{IN}	Input Current	$V_{IN} = 0V$ or V_{CC}	-20		20	μA
I_{OZ}	Disabled Output Leakage Current	$V_{OUT} = 0V$ or 3.6V	-20		20	μA
$I_{I(OFF)}$	Power-Off Input Current	$V_{CC} = 0V$, $V_{IN} = 0V$ or 3.6V	-20		20	μA
V_{IK}	Input Clamp Voltage	$I_{IK} = -18$ mA	-1.5	-0.8		V
I_{CC}	Power Supply Current	No Load, $V_{IN} = 0V$ or V_{CC} , Driver Enabled		5	8	mA
		$R_L = 100\Omega$, Driver Disabled		1.7	4	
		$R_L = 100\Omega$, $V_{IN} = 0V$ or V_{CC} , Driver Enabled		9	16	

Note 2: All typical values are at $T_A = 25^\circ C$ and with $V_{CC} = 3.3V$.

AC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 3)	Max	Units
t_{PLHD}	Differential Propagation Delay LOW-to-HIGH	$R_L = 100\ \Omega$, $C_L = 10\ \text{pF}$, See Figure 2 (Note 7), and Figure 3	0.6	1.1	1.7	ns
t_{PHLD}	Differential Propagation Delay HIGH-to-LOW		0.6	1.2	1.7	ns
t_{TLHD}	Differential Output Rise Time (20% to 80%)		0.4		1.2	ns
t_{THLD}	Differential Output Fall Time (80% to 20%)		0.4		1.2	ns
$t_{SK(P)}$	Pulse Skew $ t_{PLH} - t_{PHL} $				0.4	ns
$t_{SK(LH)}$	Channel-to-Channel Skew (Note 4)			0.05	0.3	ns
$t_{SK(HL)}$	Channel-to-Channel Skew (Note 4)				0.3	ns
$t_{SK(PP)}$	Part-to-Part Skew (Note 5)			1.0	ns	
f_{MAX}	Maximum Frequency (Note 6)	$R_L = 100\ \Omega$, See Figure 6 (Note 7)	200	250		MHz
t_{ZHD}	Differential Output Enable Time from Z to HIGH	$R_L = 100\ \Omega$, $C_L = 10\ \text{pF}$, See Figure 4 (Note 7), and Figure 5		1.7	5.0	ns
t_{ZLD}	Differential Output Enable Time from Z to LOW			1.7	5.0	ns
t_{HZD}	Differential Output Disable Time from HIGH to Z			2.7	5.0	ns
t_{LZD}	Differential Output Disable Time from LOW to Z			2.7	5.0	ns
C_{IN}	Input Capacitance			4.2		pF
C_{OUT}	Output Capacitance			5.2		pF

Note 3: All typical values are at $T_A = 25^\circ\text{C}$ and with $V_{CC} = 3.3\text{V}$.

Note 4: $t_{SK(LH)}$, $t_{SK(HL)}$ is the skew between specified outputs of a single device when the outputs have identical loads and are switching in the same direction.

Note 5: $t_{SK(PP)}$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.

Note 6: f_{MAX} criteria: Input $t_R = t_F < 1\text{ns}$, 0V to 3V, 50% Duty Cycle; Output $V_{OD} > 250\text{mV}$, 45% to 55% Duty Cycle; all switching in phase channels.

Note 7: Test Circuits in Figures 2, 4, 6 are simplified representations of test fixture and DUT loading.

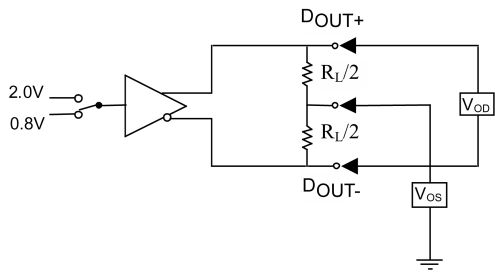
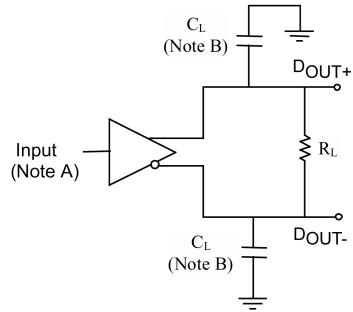


FIGURE 1. Differential Driver DC Test Circuit



Note A: All input pulses have frequency = 10 MHz, t_R or $t_F = 1$ ns
 Note B: C_L includes all fixture and instrumentation capacitance

FIGURE 2. Differential Driver Propagation Delay and Transition Time Test Circuit

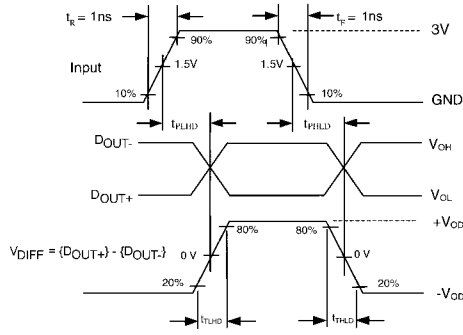
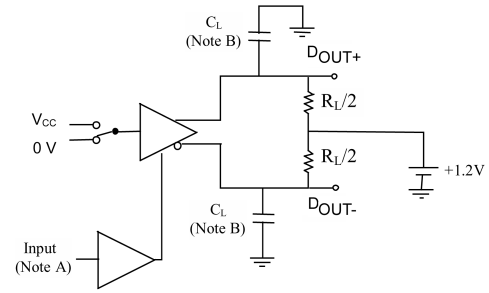


FIGURE 3. AC Waveforms



Note B: All input pulses have the frequency = 10 MHz, t_R or $t_F = 1$ ns
 Note A: C_L includes all fixture and instrumentation capacitance

FIGURE 4. Differential Driver Enable and Disable Test Circuit

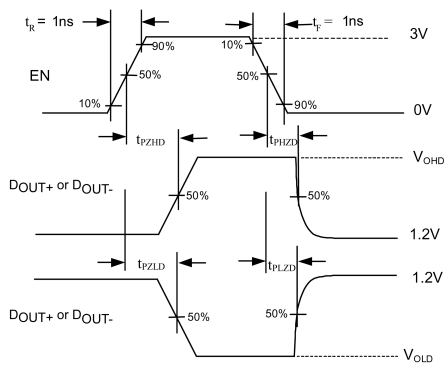


FIGURE 5. Enable and Disable AC Waveforms

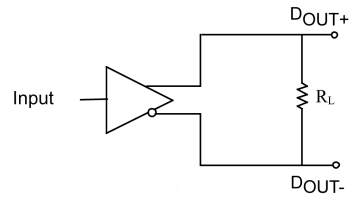


FIGURE 6. f_{MAX} Test Circuit

DC / AC Typical Performance Curves

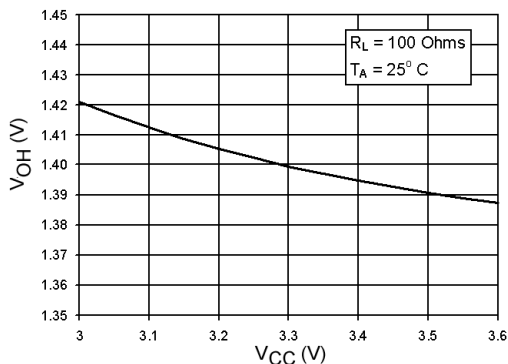


FIGURE 7. Output High Voltage vs. Power Supply Voltage

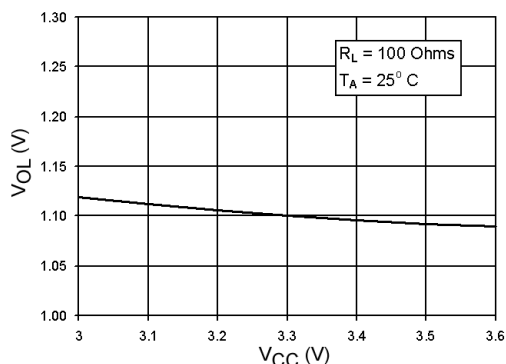


FIGURE 8. Output Low Voltage vs. Power Supply Voltage

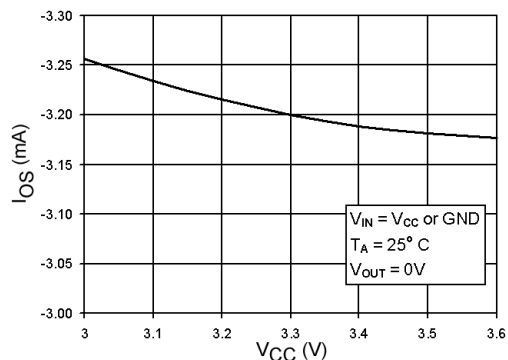


FIGURE 9. Output Short Circuit Current vs. Power Supply Voltage

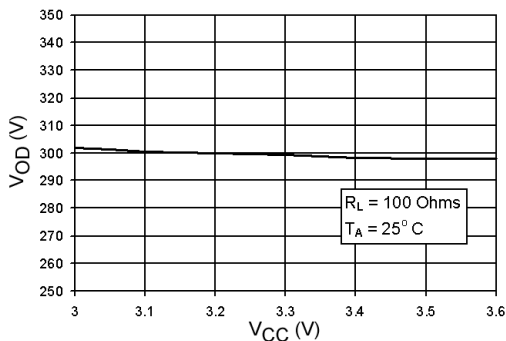


FIGURE 10. Differential Output Voltage vs. Power Supply Voltage

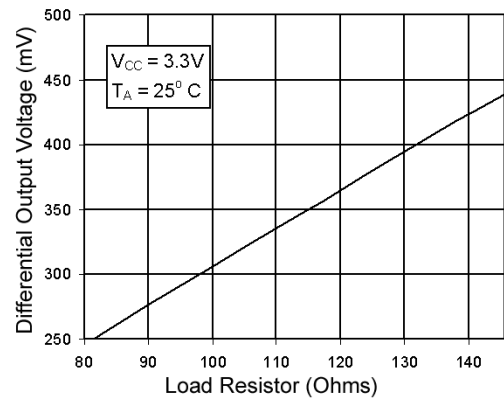


FIGURE 11. Differential Output Voltage vs. Load Resistor

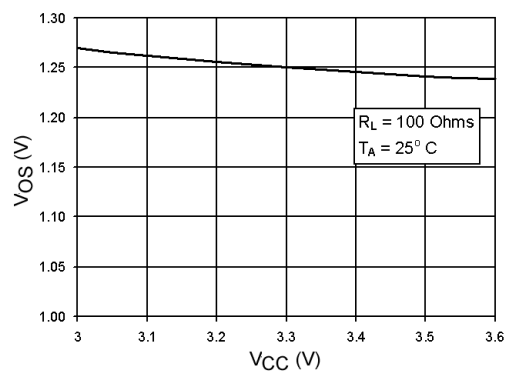


FIGURE 12. Offset Voltage vs. Power Supply Voltage

DC / AC Typical Performance Curves (Continued)

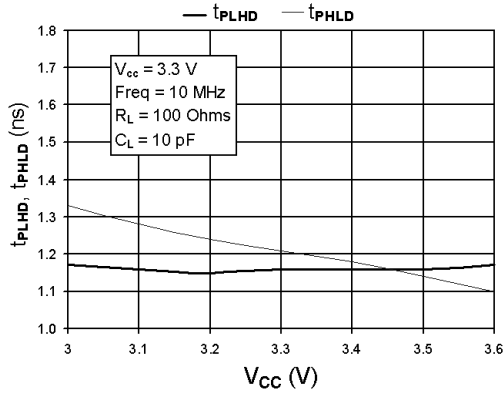


FIGURE 13. Differential Propagation Delay vs. Power Supply Voltage

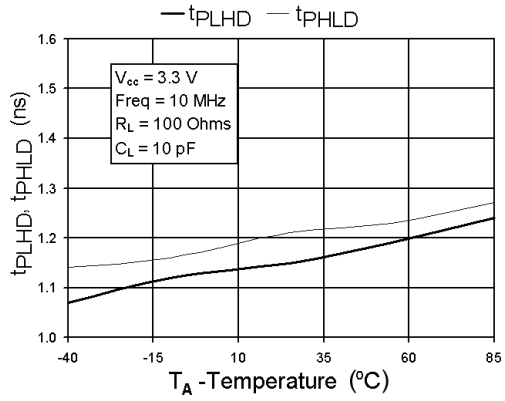


FIGURE 14. Differential Propagation Delay vs. Ambient Temperature

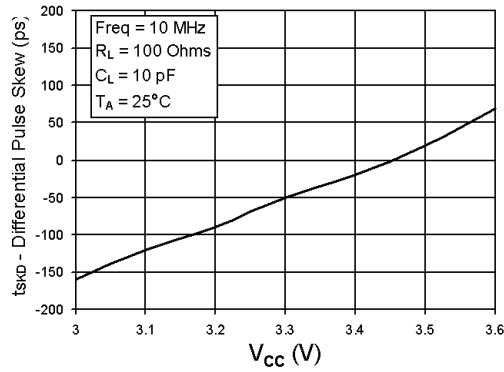


FIGURE 15. Differential Pulse Skew ($t_{PLH} - t_{PHL}$) vs. Power Supply Voltage

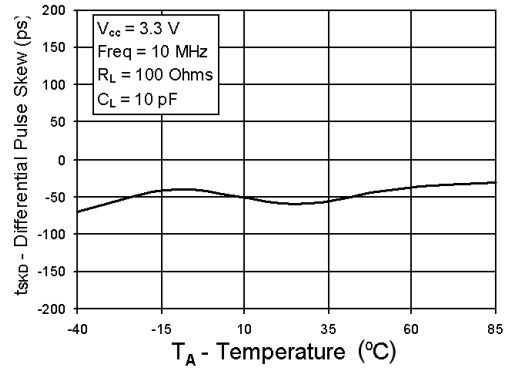
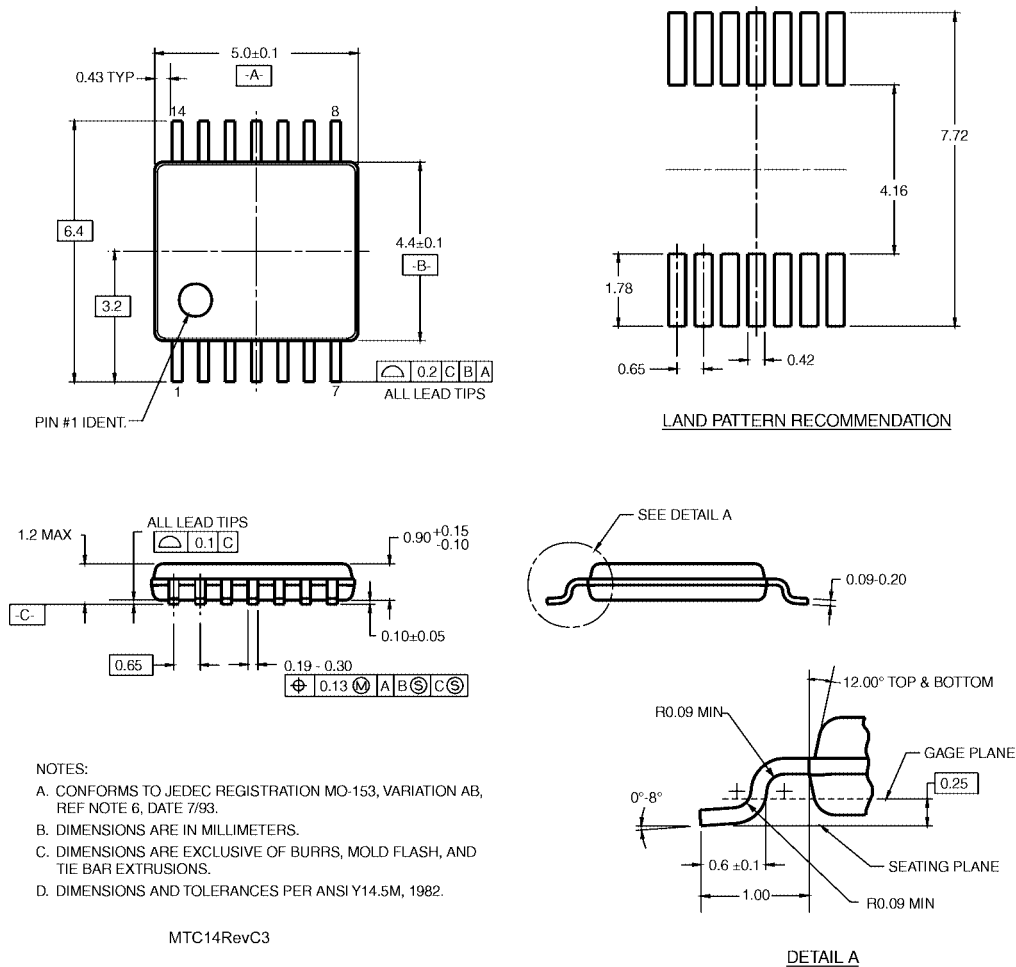


FIGURE 16. Differential Pulse Skew ($t_{PLH} - t_{PHL}$) vs. Ambient Temperature

Physical Dimensions inches (millimeters) unless otherwise noted



- NOTES:
- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.
 - DIMENSIONS ARE IN MILLIMETERS.
 - DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC14RevC3

14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View FIN1025MTCX on WIN SOURCE](#)
- ⊖ [Fairchild/ON Semiconductor Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management